© C	terial Composit opyright 2005. IPC, 1 rnational and Pan-An	Bannockb	urn, Illinois. A	ll rights reserved utions.	inder both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	within the manufactu level materials for v	arer listed i which the r	tem. Note: it nanufacturer	f the item is an as has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information				
upplier Information	I														
Company name* Co			Company uni	Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi											2025-07	2025-07-31			
Contact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative* Tit			Title - Representative			Phone - Representative*				Email -	Email - Representative*				
Product-Env-Stewards Pro			Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item	: Item Number Mfr Item N		Number Mfr Item Name				Effective Date Version		M	Manufacturing Site		Weight*	UOM	Unit Type	
		NVMFS6H852NT1G		Trench 8 80V NFET			2025-07-31		M	MY1		107.2528	mg	Each	
Anufacturing Proce	cess Information	l									I				
Terminal Plating / Grid Array Material Termina		erminal Base A	Base Alloy J-STD-020 MSL		L Rating	Peak Proc	rocess Body Temperature		e Max Time at Peal	k Tempera	ure Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU A			U Alloy	y 1			260 C 30		seconds 3						
omments															
vel 1 - maximum time at	peak temperature d	luring sol	dering is 10-3	0 seconds											
or more information rega	arding material com	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	13.512	mg	Supplier	Zinc (Zn)	7440-66-6		0.0162	mg
			Supplier	Iron (Fe)	7439-89-6		0.3175	mg
			Supplier	Copper (Cu)	7440-50-8		13.1742	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0041	mg
Die	0.727	mg	Supplier	Silicon (Si)	7440-21-3		0.727	mg
Die Attach Solder	1.4993	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			А	Lead (Pb)	7439-92-1	7a	1.3869	mg
			Supplier	Tin (Sn)	7440-31-5		0.075	mg
Lead Frame	42.5398	mg	Supplier	Silver (Ag)	7440-22-4		0.0255	mg
			Supplier	Iron (Fe)	7439-89-6		0.0425	mg
			Supplier	Copper (Cu)	7440-50-8		42.459	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0128	mg
Mold Compound-Black	48.7198	mg		Epoxy resin	proprietary data		3.654	mg
			Supplier	Phenolic Resin	Proprietary Data		1.218	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.654	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9502	mg
Plating	0.2183	mg	Supplier	Tin (Sn)	7440-31-5		0.2183	mg
Wire Bond - Cu	0.0366	mg	Supplier	Copper (Cu)	7440-50-8		0.0366	mg